
Table of Contents

1.0 PURPOSE OF THIS TECHNICAL REPORT.....	1
2.0 SCOPE AND PURPOSE OF IEC 61000-4-2.....	1
2.1 (CORRECT) USAGE OF IEC SPEC.....	1
2.1.1 <i>Climatic and Electromagnetic Conditions</i>	1
2.1.2 <i>Operations of EUT</i>	2
2.1.3 <i>Present Execution of Tests</i>	2
2.1.4 <i>Definition of Failure</i>	2
2.2 KNOWN PROBLEMS USING IEC 61000-4-2 GUNS ON SYSTEM LEVEL	2
2.3 CURRENT STATUS OF USE OF IEC GUNS ON COMPONENTS / DEVICES	3
2.3.1 <i>Use of ESD Guns in the Semiconductor Industry</i>	3
2.3.2 <i>Recent Literature</i>	3
2.4 WHY INDUSTRY IS MISUSING IEC STANDARD (APPLICATION TO DEVICES) - REQUIREMENTS OF SYSTEM VENDORS TO IC VENDORS	3
2.5 BASIC PROBLEMS TO ESTABLISH A LINK BETWEEN DEVICE LEVEL ROBUSTNESS AND SYSTEM LEVEL ROBUSTNESS	4
3.0 MOTIVATION FOR THE NEW HMM TEST METHOD.....	5
3.1 SYSTEM LEVEL TESTING AND QUALIFICATION	5
3.2 HUMAN METAL MODEL	5
3.3 AIR DISCHARGE TESTING.....	6
3.4 POWERED AND UN-POWERED TESTED STATES	6
3.5 TYPES OF FAILURES OBSERVED DURING SYSTEM LEVEL TESTING OF DEVICES.....	6
4.0 THE HMM DRAFT STANDARD PRACTICE.....	8
4.1 REQUIREMENTS OF THE SP	8
4.2 SCOPE AND PURPOSE OF THE SP	8
4.3 LIMITATIONS AND APPLICABILITY OF THE SP	9
5.0 SUMMARY.....	9
6.0 REFERENCES.....	10
 FIGURES	
Figure 1 Blown Metal Lead	7
Figure 2 Silicon Damage.....	7
Figure 3 An EMMI Image	7